



## P-Ch 150V Fast Switching MOSFETs

### Description

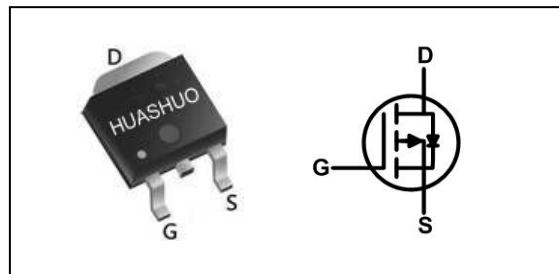
The HSU30P15 uses advanced trench MOSFET technology to provide excellent  $R_{DS(ON)}$  and gate charge for use in a wide variety of other applications.

The HSU30P15 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

### Product Summary

$V_{DS}$	-150	V
$R_{DS(ON),typ}$	85	mΩ
$I_D$	-30	A

### TO-252 Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-150	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-30	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-18	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-90	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	420	mJ
$I_{AS}$	Avalanche Current	-35	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation <sup>4</sup>	57	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	2.2	°C/W



**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=-250\mu\text{A}$	-150	---	---	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-15\text{A}$	---	85	100	$\text{m}\Omega$
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{D}}=-10\text{A}$	---	90	110	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=-250\mu\text{A}$	-1	-1.65	-2.5	V
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-150\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	-1	$\mu\text{A}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-150\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	-100	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=-5\text{V}$ , $I_{\text{D}}=-15\text{A}$	---	44	---	S
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1.6	---	$\Omega$
$Q_g$	Total Gate Charge	$V_{\text{DS}}=-75\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-15\text{A}$	---	120	---	nC
$Q_{\text{gs}}$	Gate-Source Charge		---	21	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	25	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=-75\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $R_g=6\Omega$ , $I_{\text{D}}=-15\text{A}$	---	17	---	ns
$T_r$	Rise Time		---	89	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	49	---	
$T_f$	Fall Time		---	60	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-75\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	8600	---	pF
$C_{\text{oss}}$	Output Capacitance		---	155	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	116	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	-30	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1.3	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=-75\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $L=0.1\text{mH}$ , $I_{\text{AS}}=-35\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_{\text{D}}$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.



### Typical Characteristics

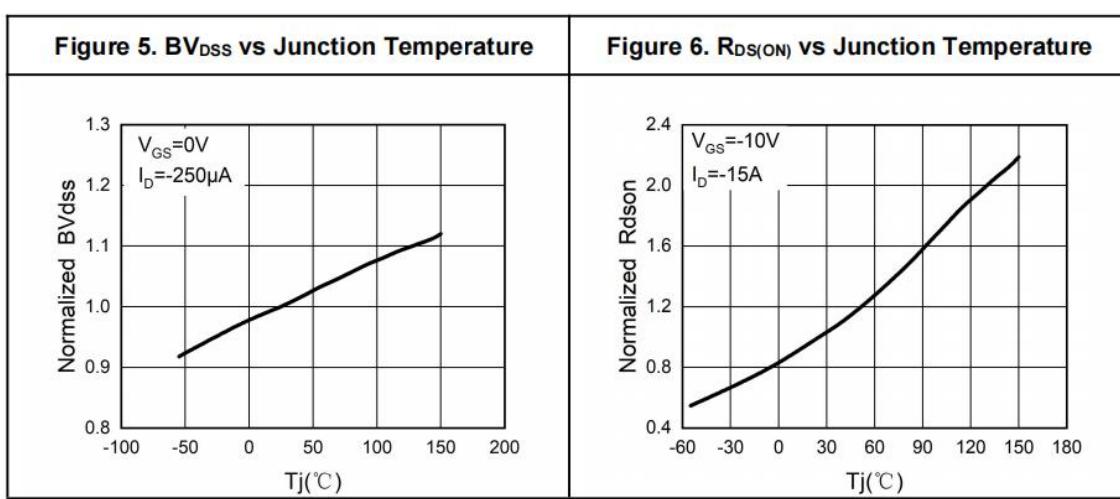
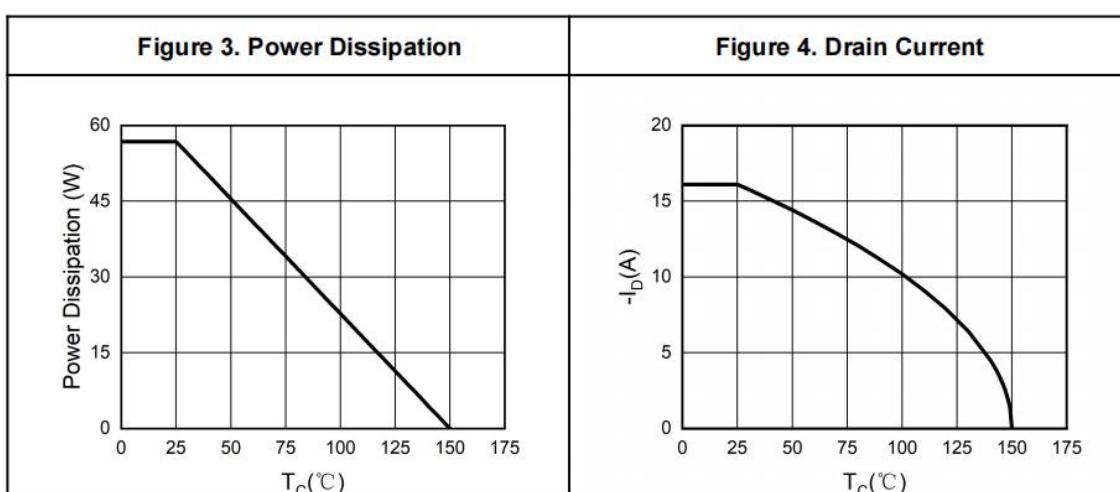
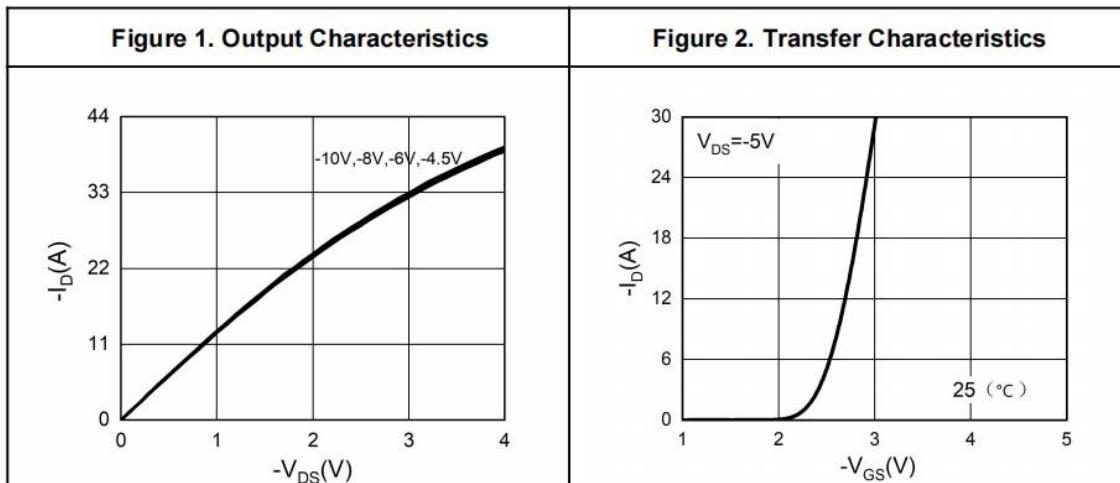




Figure 7. Gate Charge Waveforms

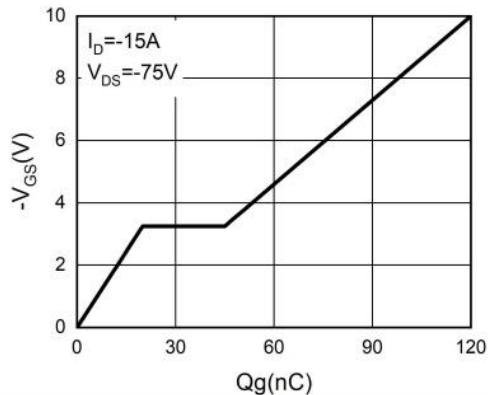


Figure 8. Capacitance

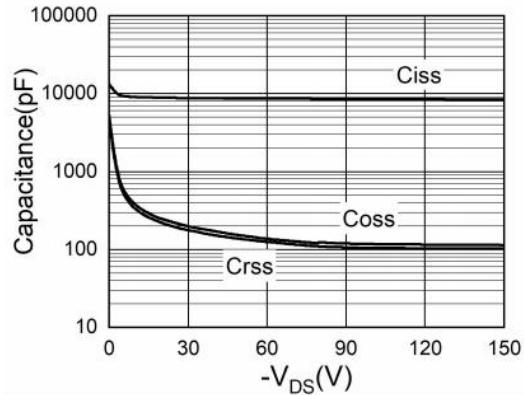


Figure 9. Body-Diode Characteristics

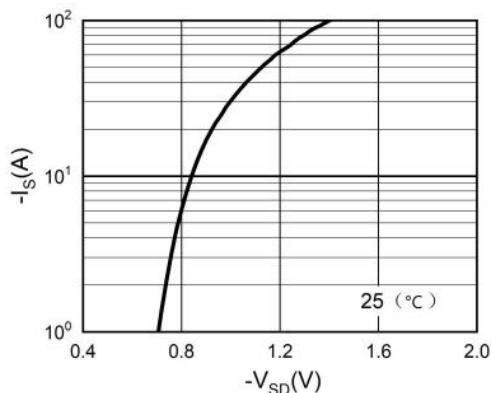
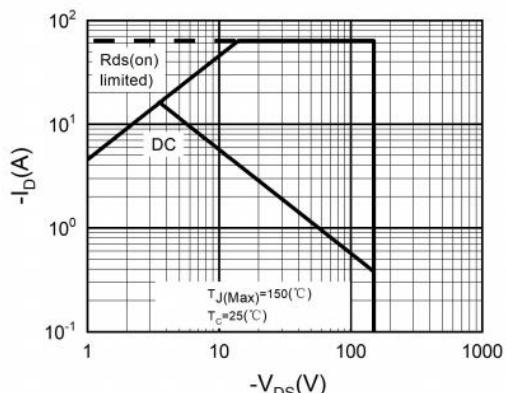
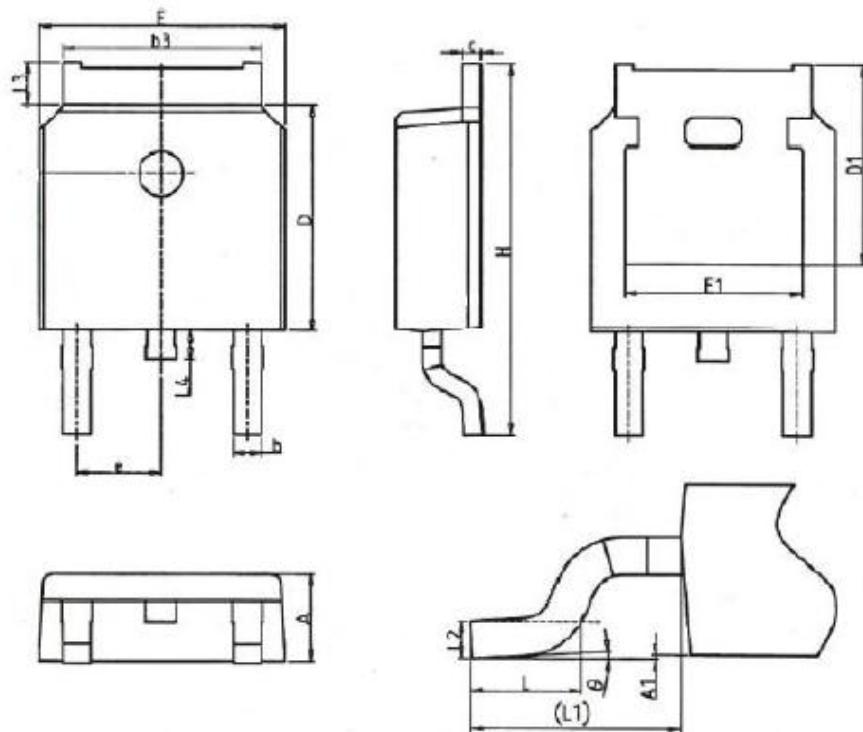


Figure 10. Maximum Safe Operating Area





## TO252-2L Package Outline



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.18	2.40	0.086	0.095
A1	-	0.2	-	0.008
b	0.68	0.9	0.026	0.036
b3	4.95	5.46	0.194	0.215
c	0.43	0.89	0.017	0.035
D	5.97	6.22	0.235	0.245
D1	5.300REF		0.209REF	
E	6.35	6.73	0.250	0.265
E1	4.32	--	0.170	-
e	2.286BSC		0.09BSC	
H	9.4	10.5	0.370	0.413
L	1.38	1.78	0.054	0.070
L1	2.90REF		0.114REF	
L2	0.51BSC		0.020BSC	
L3	0.88	1.28	0.034	0.050
L4	0.5	1	0.019	0.039
Θ	0°	8°	0°	8°